

LOW-PIN-COUNT CHIP PACKAGE AND MANUFACTURING

METHOD THEREOF

Abstract

5 A low-pin-count chip package including a die pad for receiving a semiconductor chip and a plurality of connection pads electrically coupled to the semiconductor chip wherein the die pad and the connection pads have a concave profile. A package body is formed over the semiconductor chip, the die pad and the connection pads in a manner that a portion of the die pad and a portion of each connection pad extend outward from the bottom of the package body. The present invention further provides a novel method of producing the low-pin-count chip package described above.

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